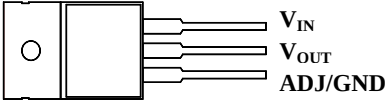
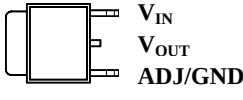
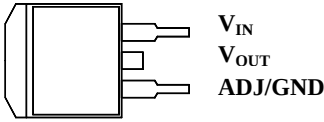
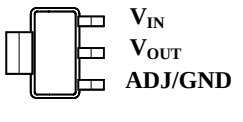




AMC7587

1.5A Low DROPOUT REGULATOR

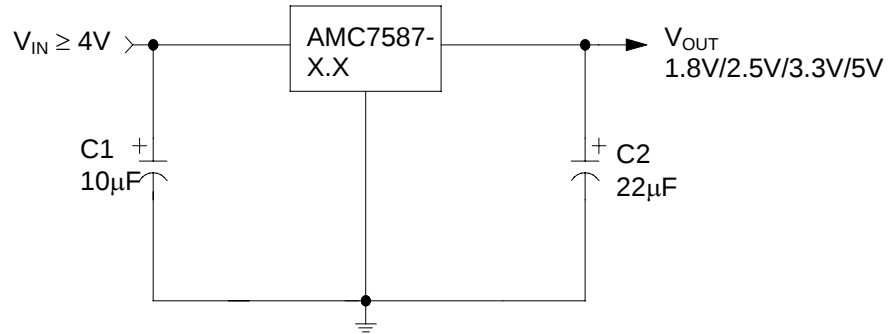
DESCRIPTION	FEATURES
The AMC7587 is a high performance low dropout regulator rated for 1.5A output current with fixed 1.8V/2.5V/3.3V/5.0V and adjustable output. It is designed for use in applications requiring low dropout characteristics over the rated current range. On chip trimming adjusts the reference voltage to 1%. These features are ideal for low voltage microprocessor applications requiring a regulated 2.5V to 3.6V power supply. In addition, the AMC7587 provides the device protections including over current and thermal shutdown. Also, reverse battery protection scheme limits the reverse current when the input voltage falls below the output.	■ Input-Output differential of typical 1.1V at 1.5A and low quiescent current ■ Output current is excess of 1.5A □ Fast transient response □ Reverse battery protection □ Short circuit protection □ Internal thermal overload protection □ Available in 3L plastic TO-220, surface mount 3L TO-263/252, and SOT223 packages □ Pin assignment identical to EZ1585B and LT1585A series.

APPLICATIONS	PACKAGE PIN OUT
■ Pentium® Processor Supplies ■ PowerPC™ Supplies ■ Computer Add-On Cards ■ Other Applications Requiring Low Dropout Voltage Over Rated Current.	 3-Pin Plastic TO-220 (T) (Top View)  3-Pin Plastic TO-252(SJ) Surface Mount (Top View)  3-Pin Plastic TO-263(ST) Surface Mount (Top View)  3-Pin Plastic SOT-223(SK) Surface Mount (Top View)

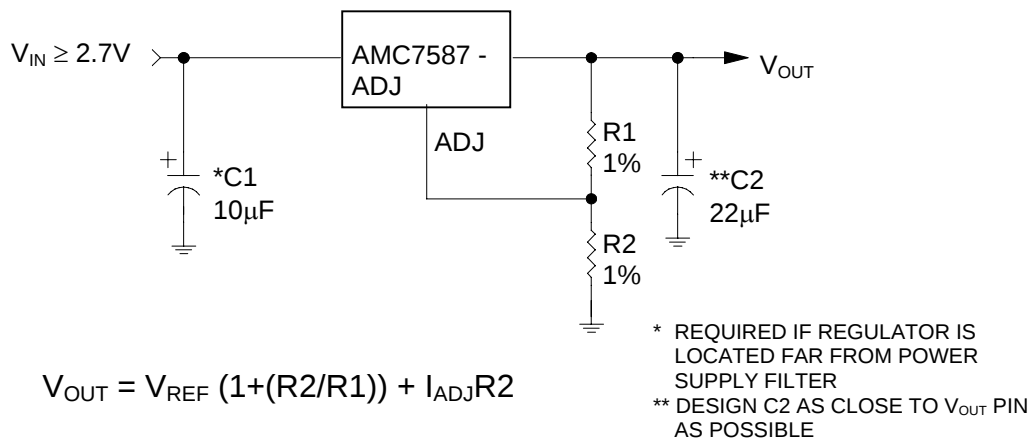
AMC7587-1.8 – 1.8V Fixed
AMC7587-2.5 – 2.5V Fixed
AMC7587-3.3 – 3.3V Fixed
AMC7587-5.0 – 5.0V Fixed
AMC7587-ADJ – Adjustable

ORDER INFORMATION							
T _A (°C)	T	TO-220	ST	TO-263	SK	SOT-223	SJ
		3-pin		3-pin		3-pin	3-pin
0 to 70		AMC7587-X.XT		AMC7587-X.XST		AMC7587-X.XSK	AMC7587-X.XSJ
		AMC7587-X.XTF(Lead Free)		AMC7587-X.XSTF(Lead Free)		AMC7587-X.XSKF(Lead Free)	AMC7587-X.XSJF(Lead Free)
		AMC7587-ADJT		AMC7587-ADJST		AMC7587-ADJSK	AMC7587-ADJSJ
		AMC7587-ADJTf(Lead Free)		AMC7587-ADJSTf(Lead Free)		AMC7587-ADJSKf(Lead Free)	AMC7587-ADJSJf(Lead Free)
Note: 1.All surface-mount packages are available in Tape & Reel. Append the letter "T" to part number (i.e., AMC7587-X.XSTT, AMC7587-X.XSKT, AMC7587-X.XSJT). 2.The letter "F" is marked for Lead Free process .							

TYPICAL APPLICATION



AMC7587-X.X application schematic



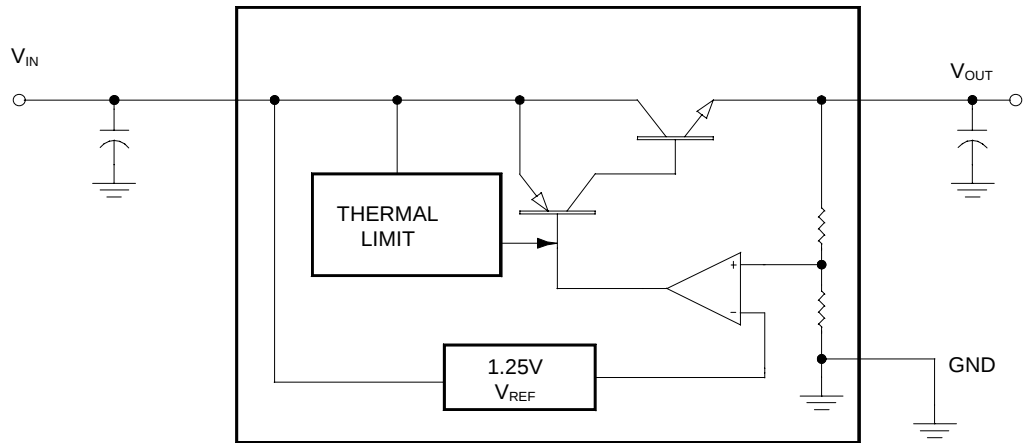
AMC7587-ADJ application schematic

ABSOLUTE MAXIMUM RATINGS (Note 1)	
Input Voltage (V_{IN})	7 V
Operating Junction temperature	150 °C
Storage Temperature Range	-65 °C to 150 °C
Lead temperature (Soldering, 10 seconds)	300 °C
Note 1: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. Currents are positive into, negative out of the specified terminal.	

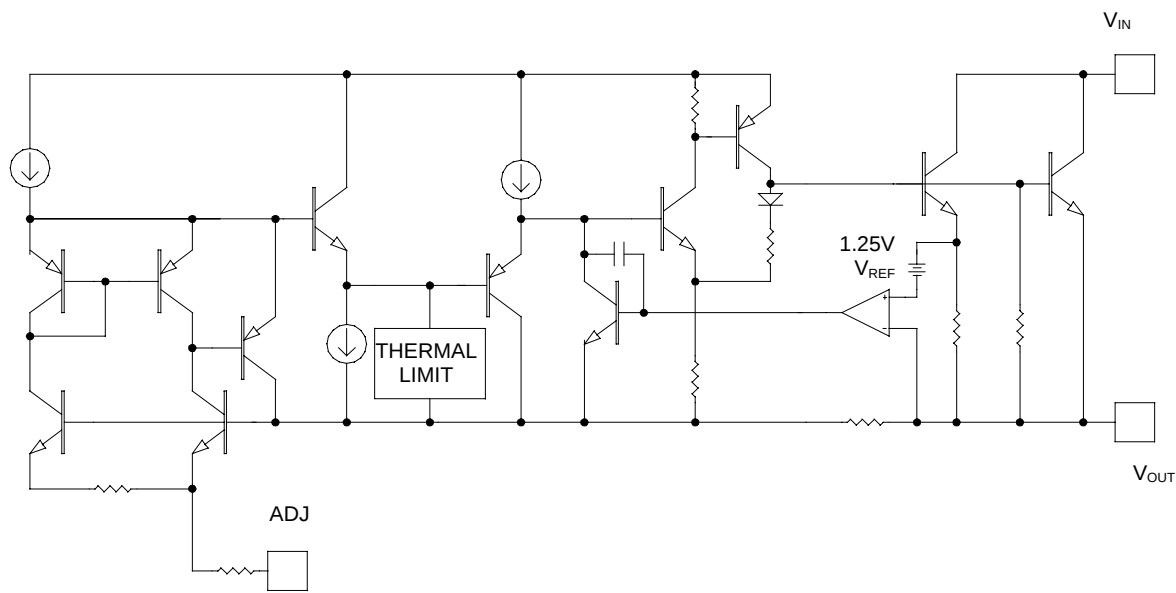
POWER DISSIPATION TABLE					
Package	θ_{JA} (°C / W)	Derating factor (mW/°C) $T_A \geq 25^\circ\text{C}$	$T_A \leq 25^\circ\text{C}$ Power rating(mW)	$T_A = 70^\circ\text{C}$ Power rating(mW)	$T_A = 85^\circ\text{C}$ Power rating (mW)
T	45	22.2	2775	1776	1443
TF	45	22.2	2775	1776	1443
ST/ST3	45	22.2	2775	1776	1443
ST/ST3F	45	22.2	2775	1776	1443
SJ	80	12.5	1562	1000	812
SJF	80	12.5	1562	1000	812
SK	136	7.35	919	588	478
SKF	136	7.35	919	588	478
Note :					
1. θ_{JA} : Thermal Resistance-Junction to Ambient, D_F : Derating factor, P_o : Power consumption. Junction Temperature Calculation: $T_J = T_A + (P_D \times \theta_{JA})$, $P_o = D_F \times (T_J - T_A)$ The θ_{JA} numbers are guidelines for the thermal performance of the device/PC-board system. All of the above assume no ambient airflow.					
2. θ_{JT} : Thermal Resistance-Junction to Tab, T_C : case(Tab) temperature, $T_J = T_C + (P_D \times \theta_{JT})$ For T and ST/ST3 packages, $\theta_{JT} = 3.0^\circ\text{C} / \text{W}$. For SJ package, $\theta_{JT} = 7.0^\circ\text{C} / \text{W}$. For SK package, $\theta_{JT} = 15.0^\circ\text{C} / \text{W}$					
3. If power consumption is over above rating, adequate heat sink is required to dissipate heat.					

RECOMMENDED OPERATING CONDITIONS					
Parameter	Symbol	Recommended Operating Conditions			Units
		Min.	Typ.	Max.	
Input Voltage	V_{IN}	2.7		7	V
Load Current (with adequate heatsinking)	I_O	0.010		1.5	A
Input Capacitor (V_{IN} to GND)		1			μF
Output Capacitor with ESR of 10 Ω max., (V_{OUT} to GND)		10			μF
Operating Ambient Temperature Range		0		70	°C

BLOCK DIAGRAM



AMC7587-X.X circuit schematic



AMC7587-ADJ circuit schematic

ELECTRICAL CHARACTERISTICS								
Unless otherwise specified, V _{IN} = V _{OUT} + 2V, I _O = 10mA. These specifications apply operating ambient temperature range, and are for DC characteristics only. (Low duty cycle pulse testing techniques are used which maintains junction and case temperatures equal to the ambient temperature.)								
Parameter		Symbol	Test Conditions	AMC7587			Units	
				Min.	Typ.	Max.		
Output Voltage	AMC7587-1.8	V _{OUT}	T _A = 25°C	1.782	1.800	1.818	V	
	AMC7587-2.5		T _A = 25°C	2.475	2.500	2.525		
	AMC7587-3.3		T _A = 25°C	3.267	3.300	3.333		
	AMC7587-5.0		T _A = 25°C	4.950	5.000	5.050		
Output Voltage	AMC7587-1.8	V _{OUT}	I _O = 10mA to 1.5A	1.771	1.800	1.829	V	
	AMC7587-2.5			2.460	2.500	2.540		
	AMC7587-3.3			3.247	3.300	3.353		
	AMC7587-5.0			4.920	5.000	5.080		
Reference Voltage	AMC7587-ADJ	V _{REF}	(Note 1)	1.238	1.250	1.262	V	
			I _O = 10mA to 1.5A, (Note 1)	1.230	1.250	1.270		
Line Regulation (Note 2)		ΔV _{OI}	(1.5V + V _{OUT}) ≤ V _{IN} ≤ 7V			0.04	0.2	%
Load regulation (Note 2)		ΔV _{OL}	I _O = 10mA to 1.5A			0.08	0.3	%
Dropout Voltage		ΔV	(Note 3)	I _O = 10mA		1.00	1.15	V
				I _O = 1.5A		1.15	1.30	
Quiescent Current (for AMC7587-X.X)		I _Q	V _{IN} ≤ 7V, I _O = 10mA to 1.5A			8	13	mA
Adjust Pin Current (for AMC7587-ADJ)		I _{ADJ}				50	120	μA
Current Limit		I _{CL}	(V _{IN} - V _{OUT}) = 2V		1.5	3		A
Minimum Load Current (Note 4)		I _{min}				5	10	mA
Ripple Rejection (Note 5)		R _R	V _{ripple} = 1V _{pp} , I _O = 100mA, fo=120 HZ		60	80		dB

Note 1 Output voltage is set to be 2.5V.

Note 2: Line and load regulations are guaranteed up to maximum power dissipation determined by input/output differential and the output current. However, the maximum power will not be available over the full input/output voltage range.

Note 3: The specifications represent the minimum input/output voltage required to maintain 1% regulation.

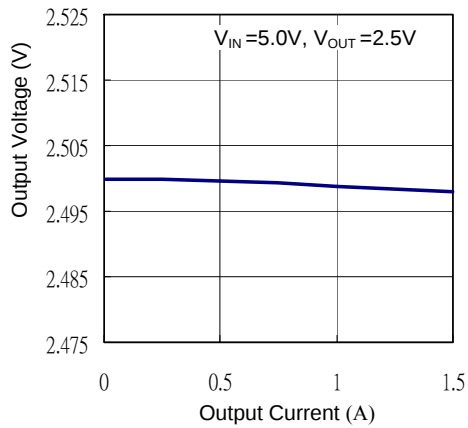
Note 4: The minimum load current is the minimum current required to maintain regulation. Normally the current in the resistor divider used to set the output voltage is selected to meet the minimum load current requirement.

Note 5: These parameters, although guaranteed, are not tested in production prior to shipment

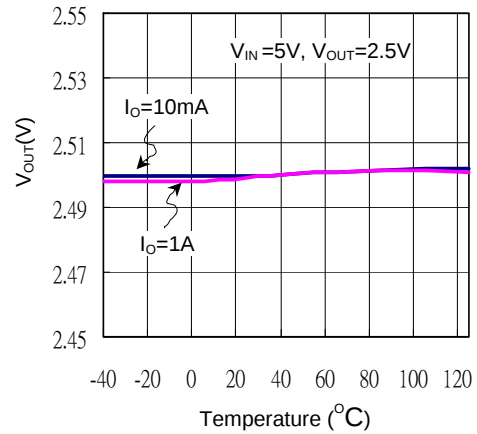
CHARACTERISTICS CURVES

$C_{IN}=10\mu F$, $C_{OUT}=22\mu F$, $T_A=25^\circ C$, unless otherwise specified.

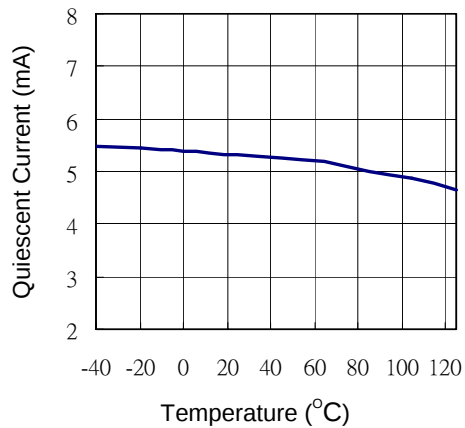
Load Regulation



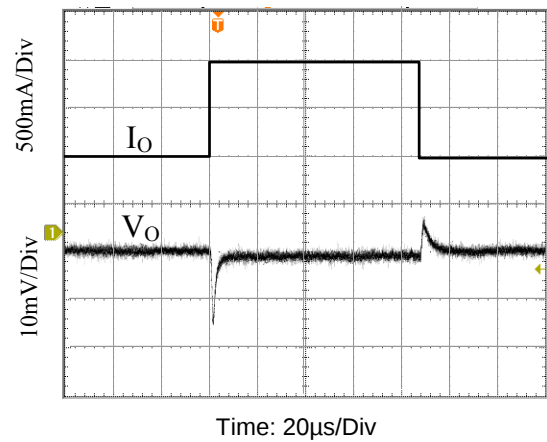
Output Voltage v.s. Temperature



Quiescent Current vs. Temperature



Load Transient Response with $I_O=1A$



APPLICATION INFORMATION:

• Thermal Consideration

Maximum Power Calculation:

$$P_{D(MAX)} = \frac{T_{J(MAX)} - T_{A(MAX)}}{\theta_{JA}}$$

$T_J(^{\circ}\text{C})$: Maximum recommended junction temperature

$T_A(^{\circ}\text{C})$: Ambient temperature of the application

$\theta_{JA}(^{\circ}\text{C/W})$: Junction-to-junction temperature thermal resistance of the package, and other heat dissipating materials.

The maximum power dissipation of a single-output regulator :

$$P_{D(MAX)} = [(V_{IN(MAX)} - V_{OUT(NOM)})] \times I_{OUT(NOM)} + V_{IN(MAX)} \times I_Q$$

Where: $V_{OUT(NOM)}$ = the nominal output voltage

$I_{OUT(NOM)}$ = the nominal output current, and

I_Q = the quiescent current the regulator consumes at $I_{OUT(MAX)}$

$V_{IN(MAX)}$ = the maximum input voltage

Then $\theta_{JA} = (150^{\circ}\text{C} - T_A)/P_D$

Thermal consideration:

When power consumption is over about 1.2W for the devices using TO-220/263 packages (687 mW for TO-252 package, 404mW for SOT223 package) at an environment of 70 $^{\circ}\text{C}$ ambient temperature, additional heat sink is required to control the junction temperature below 125 $^{\circ}\text{C}$.

The junction temperature is: $T_J = P_D (\theta_{JT} + \theta_{CS} + \theta_{SA}) + T_A$

P_D : Dissipated power.

θ_{JT} : Thermal resistance from the junction to the mounting tab of the package.

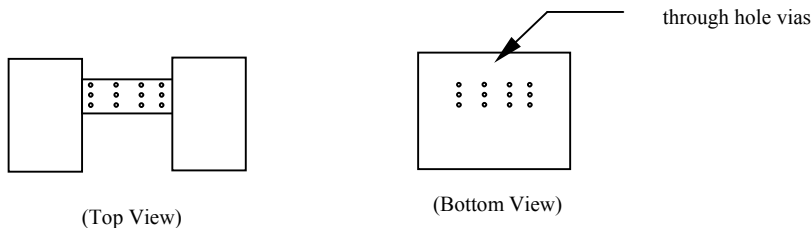
θ_{CS} : Thermal resistance through the interface between the IC and the surface on which it is mounted. (typically, $\theta_{CS} < 1.0^{\circ}\text{C/W}$)

θ_{SA} : Thermal resistance from the mounting surface to ambient (thermal resistance of the heat sink).

If PC Board copper is going to be used as a heat sink, below table can be used to determine the appropriate size of copper foil required. For multi-layered PCB, these layers can also be used as a heat sink. They can be connected with several through hole vias.

PCB $\theta_{SA} (^{\circ}\text{C} / \text{W})$	59	45	38	33	27	24	21
PCB heat sink size (mm^2)	500	1000	1500	2000	3000	4000	5000

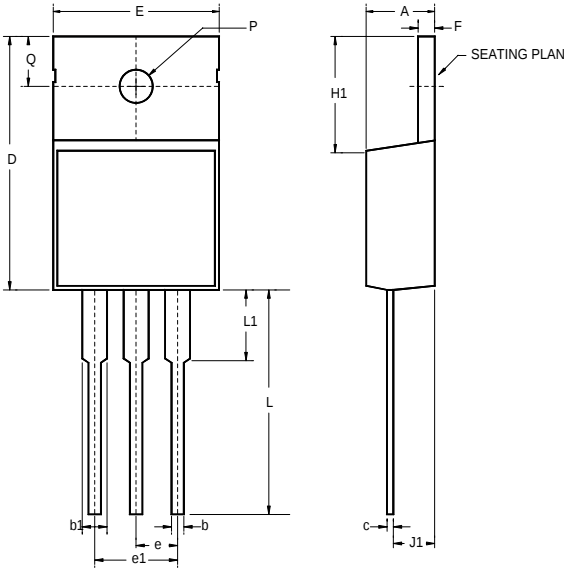
Recommended figure of PCB area used as a heat sink.



3-Pin Plastic TO-220 (T)

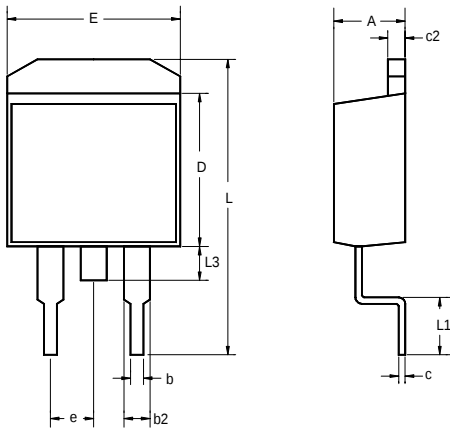
AMC7587

1.5A Low DROPOUT REGULATOR



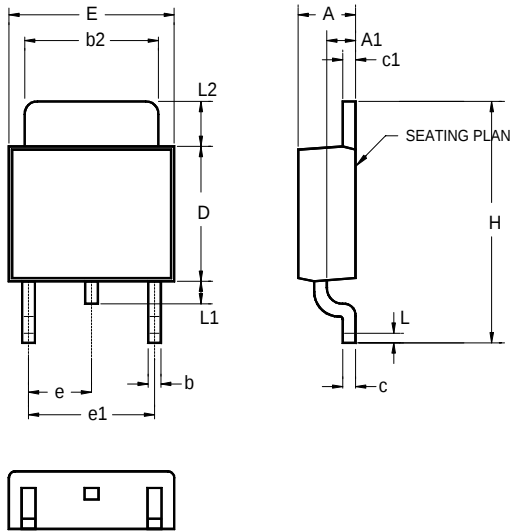
	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.140	-	0.190	3.56	-	4.83
b1	0.045	-	0.070	1.14	-	1.78
b	0.020	-	0.045	0.51	-	1.14
c	0.012	-	0.045	0.30	-	1.14
D	0.560	-	0.650	14.22	-	16.51
E	0.380	-	0.420	9.65	-	10.67
e	0.090	-	0.110	2.29	-	2.79
e1	0.190	-	0.210	4.83	-	5.33
F	0.020		0.055	0.51	-	1.40
H1	0.230	-	0.270	5.84	-	6.86
J1	0.080	-	0.115	2.03	-	2.92
L	0.500	-	0.580	12.7	-	14.73
P	0.139	-	0.161	3.53	-	4.09
Q	0.100	-	0.135	2.54	-	3.43
L1	-	-	0.250	-	-	6.35

3-Pin Surface Mount TO-263 (ST)



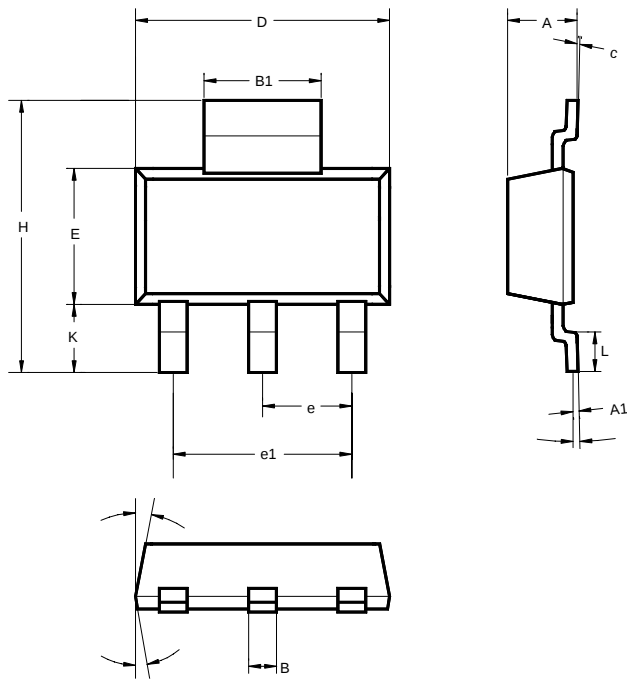
	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.160	-	0.190	4.06	-	4.83
b	0.020	-	0.039	0.51	-	0.99
b2	0.045	-	0.055	1.14	-	1.40
c	0.015 TYP.			0.38 TYP.		
c2	0.045	-	0.055	1.14	-	1.40
D	0.340	-	0.380	8.64	-	9.65
E	0.380	-	0.405	9.65	-	10.29
e	0.100 BSC			2.54 BSC		
L	0.575	-	0.625	14.61	-	15.88
L1	0.090	-	0.110	2.29	-	2.79
L2	-	-	0.115	-	-	2.92
L3	0.050	-	0.070	1.27	-	1.78

3-Pin Surface Mount TO-252 (SJ)



	INCHES			MILLIMETERS		
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.086	-	0.094	2.18	-	2.39
A1	0.040	-	0.050	1.02	-	1.27
b	-	0.024	-	-	0.61	-
b2	0.205	-	0.215	5.21	-	5.46
c	0.018	-	0.023	0.46	-	0.58
c1	0.018	-	0.023	0.46	-	0.58
D	0.210	-	0.220	5.33	-	5.59
E	0.250	-	0.265	6.35	-	6.73
e	0.090 BSC			2.29 BSC		
e1	0.180 BSC			4.58 BSC		
H	0.370	-	0.410	9.40	-	10.41
L	0.020	-	-	0.51	-	-
L1	0.025	-	0.040	0.64	-	1.02
L2	0.060	-	0.080	1.52	-	2.03

3-Pin Surface Mount SOT-223 (SK)



	MILLIMETERS		
	MIN	TYP	MAX
A	1.50	1.65	1.80
A1	0.02	0.05	0.08
B	0.60	0.70	0.80
B1	2.90	-	3.15
c	0.28	0.30	0.32
D	6.30	6.50	6.70
E	3.30	3.50	3.70
e	2.3 BSC		
e1	4.6 BSC		
H	6.70	7.00	7.30
L	0.91	1.00	1.10
K	1.50	1.75	2.00
α	0°	5°	10°
β		3°	

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